



(2,54 mm) .100"

HLE SERIES

# COST-EFFECTIVE RELIABLE SOCKET

**Mates With:**  
 TSW, MTSW, DW,  
 EW, ZW, TLW, TSM,  
 MTLW, HW

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HLE](http://www.samtec.com?HLE)

**Insulator Material:**  
 Black Liquid Crystal Polymer  
**Contact Material:**  
 BeCu  
**Plating:**  
 Au or Sn over  
 50µ" (1,27 µm) Ni  
**Current Rating (HLE/TSM):**  
 4.1 A per pin  
 (1 pin powered per row)  
**Voltage Rating:**  
 400 VAC  
**Operating Temp Range:**  
 -55°C to +125°C  
**Insertion Depth:**  
 (1,78 mm) .070" to  
 (3,43 mm) .135", pass-through,  
 or (2,59 mm) .102" min  
 plus board thickness for  
 bottom entry  
**Insertion Force:**  
 (Single contact only)  
 2 oz (0,56 N) avg.  
**Withdrawal Force:**  
 (Single contact only)  
 1.6 oz (0,44 N) avg.  
**RoHS Compliant:**  
 Yes

**Processing:**  
**Lead-Free Solderable:**  
 Yes  
**SMT Lead Coplanarity:**  
 (0,10 mm) .004" max (02-20)  
 (0,15 mm) .006" max (21-50)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

**Note:** Some lengths, styles and options are non-standard, non-returnable.

HLE	1	NO. PINS PER ROW	02	PLATING OPTION	DV	TAIL OPTION	OTHER OPTION
02 thru 50				-F = Gold flash on contact, Matte Tin on tail	Leave blank for Surface Mount	-BE = Bottom Entry (N/A with -TE)	-A = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (N/A with -TE, -PE & -LC)
				-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail			
				 (Requires -BE for Bottom Entry)	-TE = Through-Hole Top Entry	-LC = Locking Clip (2 positions min.) (N/A with -A) (Manual placement required)	
	-PE = Through-hole Pass-Through Entry	-P = Metal Pick & Place Pad (3 positions min.)					
				 -PE      -TE	 (Requires -BE for Bottom Entry)	-TR = Tape & Reel Packaging (29 positions max.)	